

구리 첨가가 Ni-MILC에 미치는 효과에 대한 연구  
Effects of Cu addition in Ni-MILC

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It has been well known that Ni-MILC TFTs are acceptable for operation of LCD devices but still decrease of annealing temperature is desirable for the future devices like LCD on the plastic substrate. In this work, Cu was added to Ni-MILC in an attempt to lower the annealing temperature and enhance the MILC rate.

It has been found that even small amount of Cu addition enhances the MILC rate considerably. Also well type MILC can be distinguished from island type, which cannot be observed in pure Ni-MILC. Poly TFTs were fabricated with Cu/Ni-MILC and the effects of copper addition on the electrical properties were carefully investigated.

Details of crystallization phenomenon and electrical properties of thus fabricated MILC poly TFTs will be presented with prospect.